

N-Ch 60V Fast Switching MOSFETs

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary

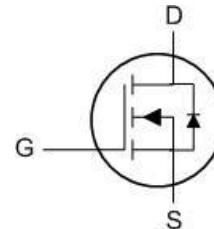
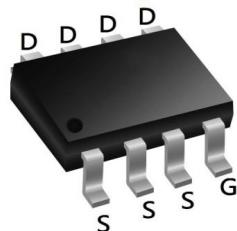


BVDSS	RDS(ON)	ID
60V	34.5mΩ	10A

Description

The XR10N06S is the high performance complementary N-ch and P-ch MOSFETs with high cell density, which provide excellent RDS(ON) and gate charge for most of the synchronous buck converter applications. The XR10N06S meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

SOP8 Pin Configuration

Absolute Maximum Ratings ($T_c=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		60	V
V_{GSS}	Gate-Source Voltage		± 20	V
I_D	Continuous Drain Current	$T_c = 25^\circ\text{C}$	10	A
		$T_c = 100^\circ\text{C}$	6.8	A
I_{DM}	Pulsed Drain Current ^{note1}		30	A
EAS	Single Pulsed Avalanche Energy ^{note2}		6.3	mJ
P_D	Power Dissipation	$T_c = 25^\circ\text{C}$	4	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		63	$^\circ\text{C}/\text{W}$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +175	$^\circ\text{C}$

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Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristics						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	60	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=60\text{V}$, $V_{\text{GS}}=0\text{V}$,	-	-	1.0	μA
I_{GSS}	Gate to Body Leakage Current	$V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=\pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_D=250\mu\text{A}$	1	1.6	2.5	V
$R_{\text{DS}(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{\text{GS}}=10\text{V}$, $I_D=15\text{A}$	-	34.5	44	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_D=10\text{A}$	-	41.5	54	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}}=25\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1.0\text{MHz}$	-	825	-	pF
C_{oss}	Output Capacitance		-	49	-	pF
C_{rss}	Reverse Transfer Capacitance		-	41	-	pF
Q_g	Total Gate Charge	$V_{\text{DS}}=30\text{V}$, $I_D=4.5\text{A}$, $V_{\text{GS}}=10\text{V}$	-	14	-	nC
Q_{gs}	Gate-Source Charge		-	2.9	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	5.2	-	nC
Switching Characteristics						
$t_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{DS}}=30\text{V}$, $I_D=2\text{A}$, $R_L=6.7\Omega$, $R_G=3\Omega$, $V_{\text{GS}}=10\text{V}$	-	5	-	ns
t_r	Turn-on Rise Time		-	2.6	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time		-	16.1	-	ns
t_f	Turn-off Fall Time		-	2.3	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current	-	-	10	-	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	30	-	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$, $I_S=15\text{A}$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	$T_J=25^\circ\text{C}$, $I_F=15\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$	-	35	-	ns
Q_{rr}	Body Diode Reverse Recovery Charge		-	53	-	nC

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition : $T_J=25^\circ\text{C}$, $V_{\text{DD}}=30\text{V}$, $V_{\text{G}}=10\text{V}$, $L=0.5\text{mH}$, $R_g=25\Omega$, $I_{\text{AS}}=6.1\text{A}$ 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

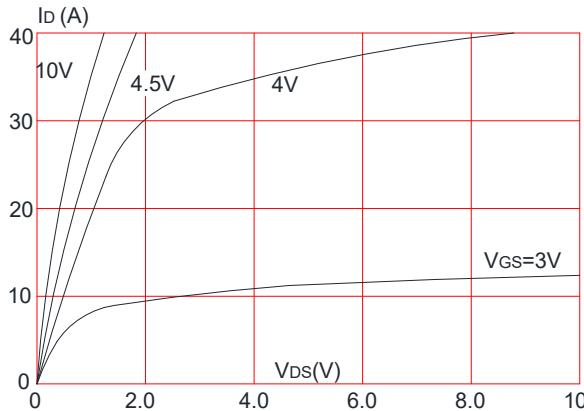


Figure 3: On-resistance vs. Drain Current

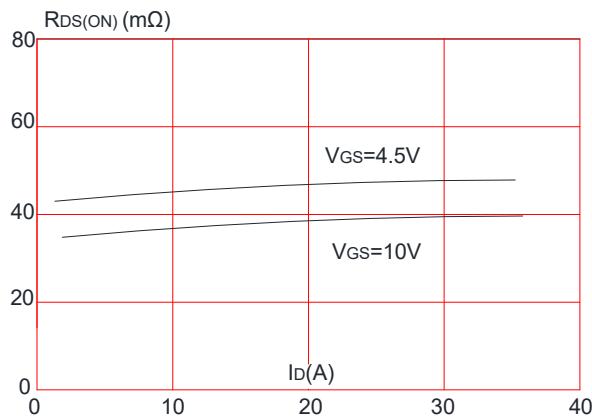


Figure 5: Gate Charge Characteristics

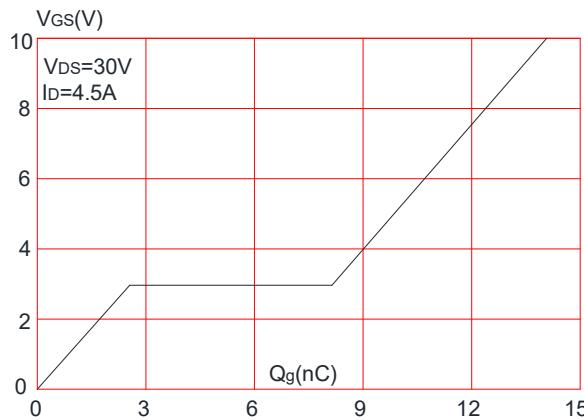


Figure 2: Typical Transfer Characteristics

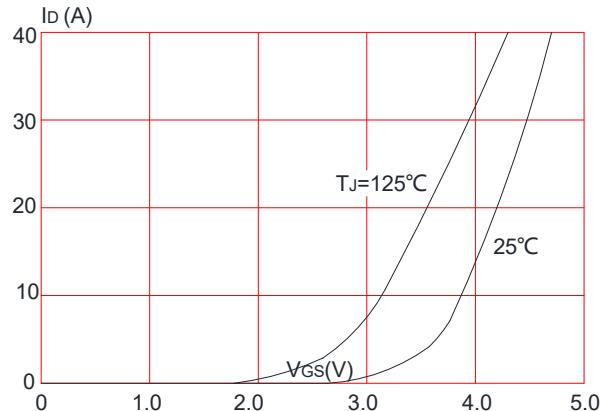


Figure 4: Body Diode Characteristics

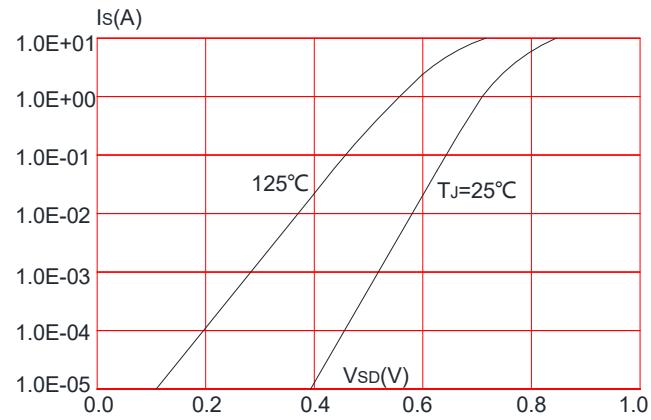
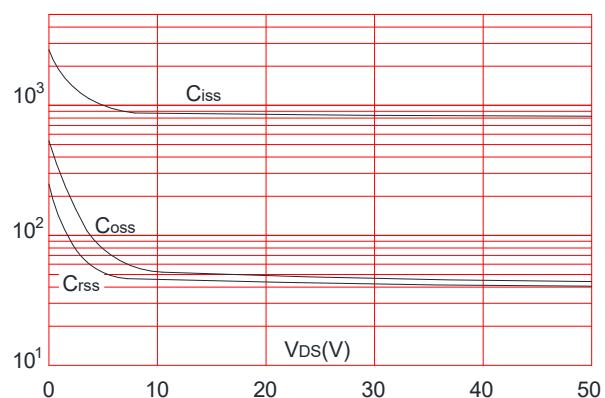


Figure 6: Capacitance Characteristics



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Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

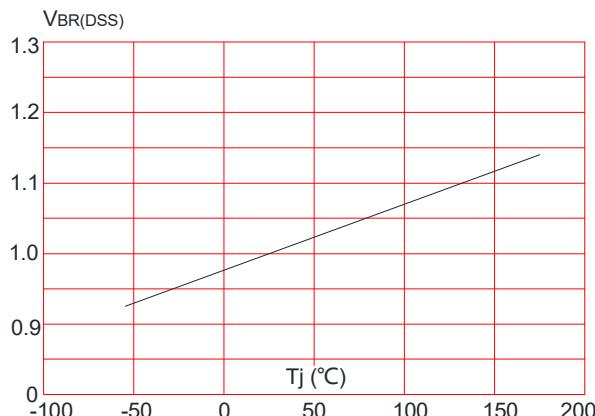


Figure 9: Maximum Safe Operating Area

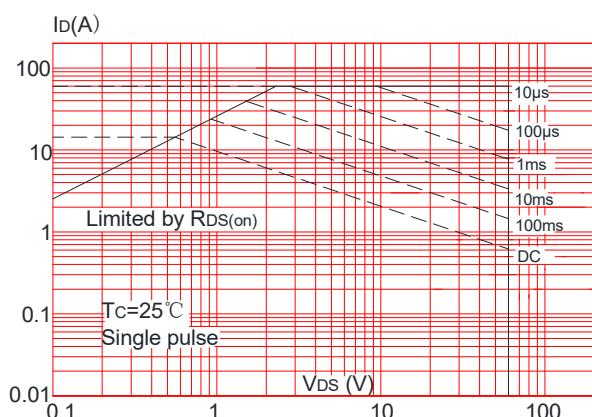


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

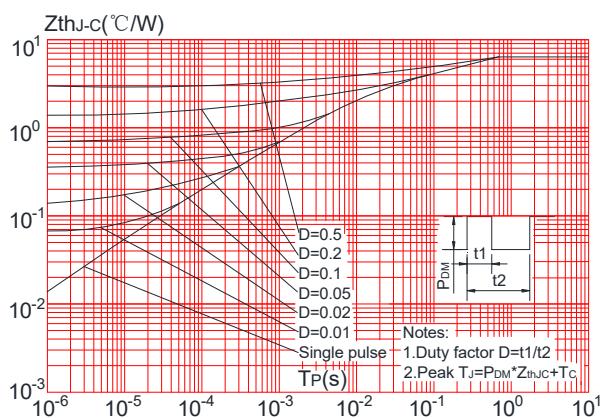


Figure 8: Normalized on Resistance vs. Junction Temperature

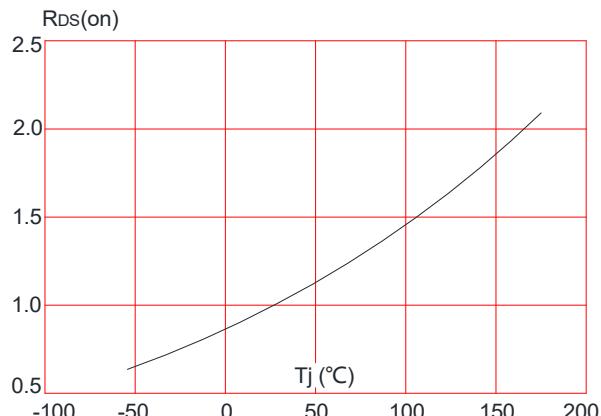
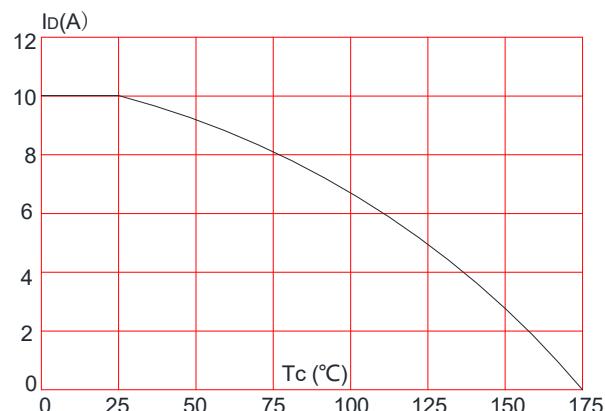
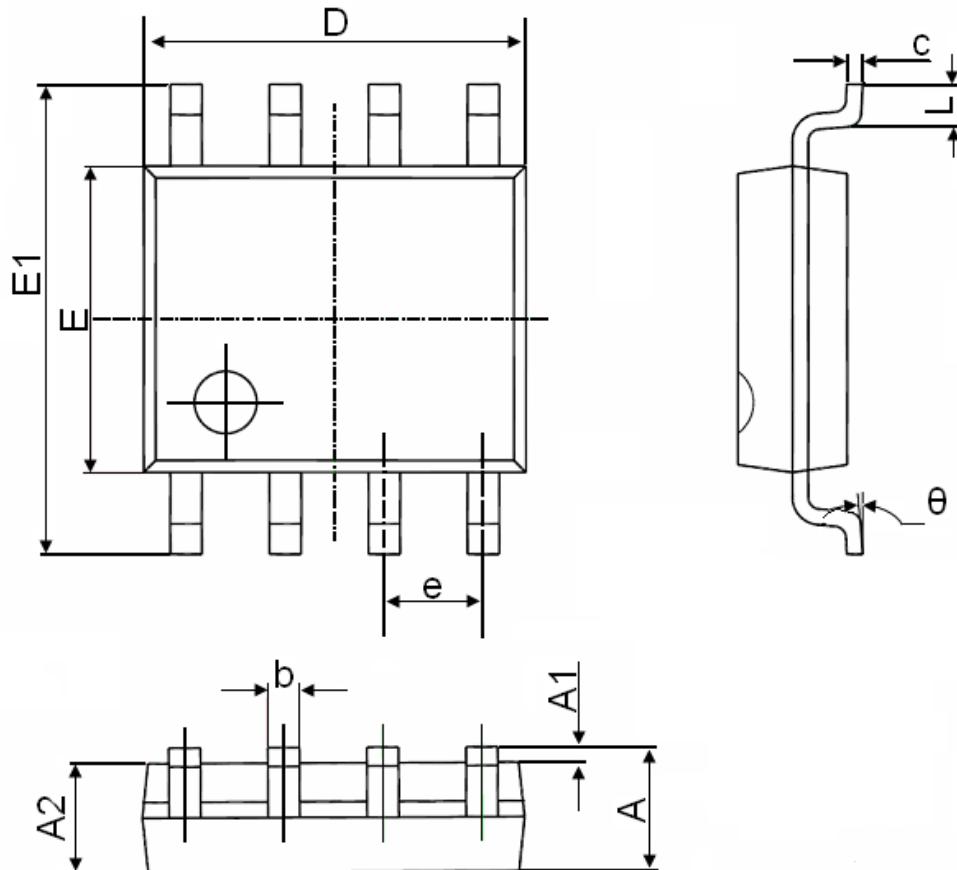


Figure 10: Maximum Continuous Drain Current vs. Case Temperature



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SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°